

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1167	(257/177,687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/23 16:45
S2	10	(("6265753") or ("6201696") or ("3453292") or ("5892289")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/23 16:46
S3	28	("4814943" "5081562" "5386342" "5398160" "5940271").PN. OR ("6201696").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/23 16:50
S4	119	(case or casing or frame or housing) near8 (fill or filled or filling or inject\$4) near8 (silicon near gel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/23 16:56
S5	7	("5928768" "6066219" "6261703" "6309737").PN. OR ("6690087").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/23 17:22
S6	1	("5986218").PN. OR ("6440574").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/23 17:26
S7	41	("5291065").URPN.	USPAT	OR	ON	2007/10/28 12:35
S8	643	(257/E23.181).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/23 17:36
S9	874	(438/121).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/24 15:06
S10	160596	(chip or die or dice or element or IC or component or (integrated near circuit) or device) near8 ((metal or conductor or conductive or conducting or electrode) near8 (base or support\$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 11:31

EAST Search History

S11	228648	(seal\$4 or encapsulat\$4 or cover\$4 or mold\$4 or barrier or protect\$4) near8 (polymer or polymerization or polyimide)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 11:34
S12	578	S10 same S11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 11:34
S13	14950	(438/106-127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/24 11:34
S14	40	S12 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/24 11:34
S15	2	("6201696").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/24 15:06
S16	4	(("6265753") or ("5892289")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:06
S17	19	("5616958" "5629566" "5641996" "5670826").PN. OR ("5892289").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 14:11
S18	2	("6201696").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:27

EAST Search History

S19	2	("5359208").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 14:28
S20	18	(partial near discharge) same (module or stack\$4 or package or packaged or packaging) same (chip or IC or element or component or (integrated near circuit) or device or die) same (wafer or substrate or carrier or board)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 14:30
S21	15	("3144704" "5155660" "5202578" "5384683" "5389743" "5424579" "5444295" "5471089" "5519252" "5521437" "5559374" "5661343" "5736234" "5956231").PN. OR ("7141741").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 14:37
S22	26	("5559374").URPN.	USPAT	OR	ON	2007/10/25 14:38
S23	5	(HV or (high near voltage)) same (silicone near gel) and (partial near discharge) and (delamination or bubbles or moisture or evaporation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 14:43
S24	11	("4814943" "5081562" "5386342" "5398160" "5940271").PN. OR ("6597063"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 14:44
S25	28	("4814943" "5081562" "5386342" "5398160" "5940271").PN. OR ("6201696"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/25 14:45
S26	4	((sealant near8 (polyimide)) near8 (corner or peripheral or edge))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 14:52

EAST Search History

S27	28613	((chip or die or element or IC or device or component or (integrated near circuit) or dice) same (wafer or substrate or carrier or board) same (plate or conductor or metal or conductive or conducting)) same (sealant near8 concave or curve or curved or curving)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 14:51
S28	9770	((sealant or (polyimide)) near8 (corner or peripheral or edge))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 14:52
S29	60	S27 and S28	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/25 15:41
S30	2	("6265753").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:41
S31	2	("6201696").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/25 15:41
S32	8	(("3453292") or ("5892289") or ("6265753")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/28 12:52
S33	329	(438/117).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/28 12:52

EAST Search History

S34	15	("20040109283" "20050051906" "20050067685" "3871015" "4545610" "5950073" "5968670" "6506681" "6552425" "6559527" "6653730" "6667548" "6673697" "6703697" "6753613").PN. OR ("7160757").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/28 13:00
S35	954	(257/687).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/28 13:00
S36	11	("4814943" "5081562" "5386342" "5398160" "5940271").PN. OR ("6597063").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/28 13:09
S37	28	("4814943" "5081562" "5386342" "5398160" "5940271").PN. OR ("6201696").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/28 13:13
S38	31	("4639759" "4916502" "4965710" "5006920" "5077595" "5291065" "5347158").PN. OR ("5521437").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/28 13:15
S39	32	("4812897" "4823234").PN. OR ("4887148").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/28 13:23
S40	27	(257/E23.183).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/10/28 13:25
S41	90378	power near8 module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:25
S42	164344	(bottom near plate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:26

EAST Search History

S43	3500335	(encapsulant or gel or silicone or fill\$4 or encapsulating)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:28
S44	806	S41 and S42 and S43	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:28
S45	800	S44 and (chip or die or element or component or IC or (integrated near circuit) or device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:29
S46	357	S45 and (polymer or polyimide or resin or Apical or Kapton or Kaptrex or polymerization or monomer or oligomer or polymerize)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:32
S47	9	("20030231841" "6318908" "6435734" "6603782" "6646291" "6655856").PN. OR ("6793410").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/10/28 13:35
S48	57736	power with (chip or die or device or component or IC or (integrated near circuit) or element) with (module or package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:39
S49	1465	(fill or filled or filling or inject\$4 or dispense\$4 or embed\$4) near8 (silicone near gel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:41
S50	136	S48 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:51

EAST Search History

S51	850489	(power near8 (device or module or component))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 13:51
S52	233284	(rigid or fixed or unmoving or inflexible or stiff\$4 or firm or tough\$4 or hard\$4 or rocky or rugged or strong or sturdy) near8 resin	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:03
S53	49	S51 same (interpos\$4 or between or sandwich\$4 or link\$4) same (silicone near gel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:02
S54	11	(rigid near8 resin) with (silicone near gel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:02
S55	112	((rigid or fixed or unmoving or inflexible or stiff\$4 or firm or tough\$4 or hard\$4 or rocky or rugged or strong or sturdy) near8 resin) with (silicone near4 gel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:04
S56	101	S55 not S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:42
S57	17854	(polyimide near8 ((epoxy near resin) or (polyester near resin)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:43
S58	88	S57 and (silicone near gel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:48

EAST Search History

S59	3559	polyimide near8 (silicone near resin)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 14:50
S60	10	S59 and (power near module)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/10/28 16:36